

Appl. No. 10/604,717
Amdt. dated February 22, 2005
Reply to Office action of December 14, 2004

REMARKS/ARGUMENTS

Claims 1-15 are rejected under 35 U.S.C. 103(a), for reasons of record that can be found on pages 2-5 in the Office action identified above. In order to more particularly point out and distinctly claim that which applicants regard as their invention, claim 1 has been amended.

The examiner has cited three prior art documents against the originally-filed claims alleging that certain combinations of them render the claims obvious under 35 USC 103. Applicants respectfully disagree. When evaluating the scope and content of the prior art and indeed even selecting those documents thought to be pertinent, one must bear in mind that the documents cited should be from the same field of endeavor as the invention and specifically that the document cited should be "reasonably pertinent to the problem addressed" by applicants. These requirements are set out by the Federal Circuit in In re Clay reported at 32 USPQ 1058 especially at page 1061 (Fed. Cir. 1992). As explained in more detail below, the cited prior art documents relied upon by the examiner are in fact not concerned with the same problem to which the present invention is directed, namely that of obtaining a highly heat-radiative backlight unit by utilizing a metal diffusion film.

Applicants would like to point out the differences between the combination of the Moon et al. (2003/0086255A1) and Hillstrom (5,983,543) and the amended claim 1 of the instant application. Moon et al. merely discloses a usual backlight device with various lamp holders to reduce the number of required lamp power lines and connectors. This reference applied by the examiner does not pertain to the use of a metal diffusion film for solving the heat accumulated in the backlight device. Hillstrom describes an outdoor menu display device, but does not teach or suggest using a metal diffusion film to

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improve heat dissipation of the device. Further, none of the above prior art suggests using a metal diffusion film to improve light use efficiency (see paragraph [0024] of the present application).

Mertz et al. (2002/0154474A1) is applied by the examiner, in combination with Moon et al. (2003/0086255A1) and Hillstrom (5,983,543), to reject claims 6-9 of the present application under 35 USC 103. Mertz et al. describes a usual heat transfer system arranged to dissipate heat generated from chips attached to a printed circuit board (see paragraph [0079]). The heat sink and the heat pipe form a thermal path from the IC chips to the top plate of the top case. Mertz et al. does not pertain to the use of a metal diffusion film for solving the heat accumulated in the backlight device.

Reconsideration of this application and favorable action are solicited. As claims 2-15 are dependent on claim 1, they should be allowed if claim 1 is allowed. Applicants respectfully request that a timely Notice of Allowance be issued in this case.

Sincerely yours,



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Winston Hsu, Patent Agent No. 41,526

P.O. BOX 506, Merrifield, VA 22116, U.S.A.

Voice Mail: 302-729-1562

Facsimile: 806-498-6673

e-mail : winstonhsu@naipo.com

Note: Please leave a message in my voice mail if you need to talk to me. The time in D.C. is 13 hours behind the Taiwan time, i.e. 9 AM in D.C. = 10 PM in Taiwan).